

IN THE CLAIMS

Please cancel claims 15-22 and add the following new claims.

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-27. (Cancelled)

28. (New) A printed circuit board comprising:

a substrate having a surface, said surface having a central region and an outer region; and

a first plurality of rows of electrical connections on said surface, each of said rows extending from the central region to the outer region;

wherein a space between every pair of adjacent rows of the first plurality of rows is progressively larger from the central region to the outer region to contain a progressively increasing number of conductive traces, said space containing no electrical connections;

wherein none of the electrical connections in each row are directly connected to one another electrically.

29. (New) The printed circuit board of claim 28, wherein said electrical

connections are selected from a group comprising input/output connections, power connections, and ground connections.

30. (New) The printed circuit board of claim 28, wherein said electrical connections comprise an array of electrically conductive bumps.

31. (New) The printed circuit board of claim 28, further comprising:
a semiconductor die coupled to the substrate and having a second plurality of rows of electrical connections positioned to match the first plurality of rows of electrical connections responsive to the semiconductor die being coupled to the substrate.

32. (New) The printed circuit board of claim 28, wherein each of said rows extends radially from the central region to the outer region.

33. (New) A printed circuit board comprising:
an integrated circuit die having a surface, said surface having a central region and an outer region; and
a first plurality of rows of electrical connections on said surface, each of said rows extending from the central region to the outer region;
a space between each adjacent row, each of the spaces containing no electrical connections;

wherein an average of all the spaces is progressively non-decreasing from the central region to the outer region.

34. (New) The printed circuit board of claim 33, wherein said average of all the spaces is progressively increasing from the central region to the outer region.

35. (New) The printed circuit board of claim 33, wherein said electrical connections comprise an array of electrically conductive bumps.

36. (New) The printed circuit board of claim 33, wherein said first plurality of rows of electrical connections are positioned on said surface in a pattern to match a second plurality of rows of electrical connections on a substrate responsive to said integrated circuit die being coupled to said substrate.

37. (New) The printed circuit board of claim 33, wherein each of said rows extends radially from the central region to the outer region.

38. (New) A printed circuit board comprising:

a substrate having a first surface, said first surface having a central region and an outer region;

a first plurality of rows of electrical connections on said first surface, each of said rows extending from the central region to the outer region, wherein a space

between ones of the electrical connections at substantially a same distance from the central region of the first plurality of rows is progressively larger from the central region to the outer region, said space containing no electrical connections; and a semiconductor die coupled to the substrate and having a second plurality of rows of electrical connections.

39. (New) The printed circuit board of claim 38, wherein a space between adjacent rows of the first plurality of rows is progressively increasing from the central region to the outer region.

40. (New) The printed circuit board of claim 38, wherein said first plurality of rows of electrical connections are positioned on said surface in a pattern to match the second plurality of rows of electrical connections responsive to said semiconductor die being coupled to said substrate.

41. (New) The printed circuit board of claim 38, wherein each of said rows extends radially from the central region to the outer region.